



Ormet Circuits Inc.

Interconnecting the next generation of electronics

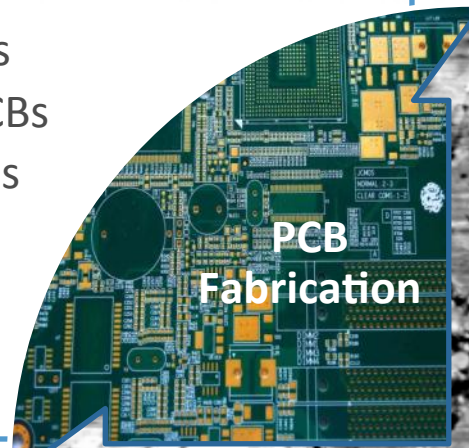
Overview

- Ormet Circuits provides conductive pastes that enable **electrical interconnection** and thermal management in electronic substrates, components and assemblies.

Ormet's Technology is a Platform Used in a Wide Range of Electronics Applications

PCB Fabrication

- Smartphones
- Advanced PCBs
- Core business



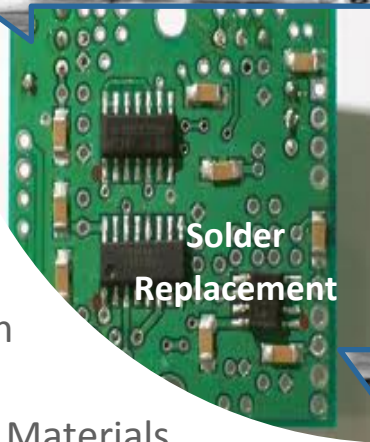
Semiconductor Packaging

- Power Semis
- LEDs
- Computer Memory



Solder Replacement

- Component Attach
- Solar Cells
- Thermal Interface Materials



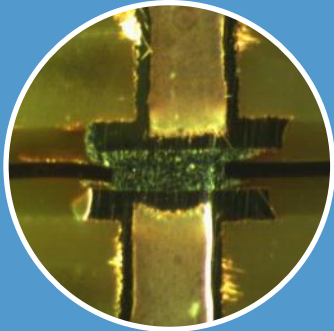
Adjacent Markets

- EMI Shielding
- Printed Electronics



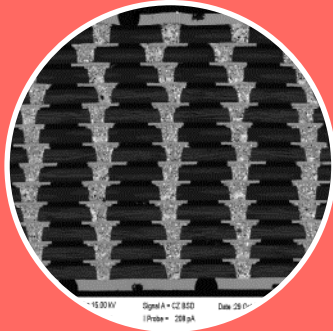
Broad market potential for 'Green' electrically conductive materials

Ormet is Focused on Markets Requiring Advanced Electrical Interconnects



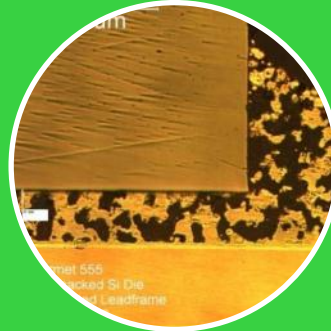
PCB Fabrication
Core to Core

High Layer Count
Printed Circuit Boards
for Device and Wafer
Test Boards



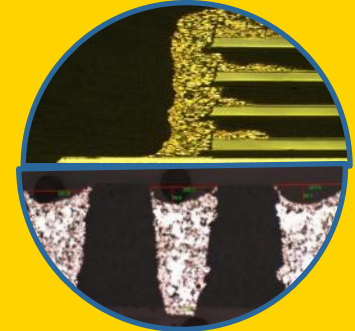
PCB Fabrication
Any-Layer
Interconnects

Printed Circuit Boards
For Smartphones and
Tablets



Semiconductor
Packaging

Power ICs
LEDs
Power Discrettes



Semiconductor
Assembly
Interconnects

Wirebond Replacement
Wafer Level Packaging

Patented sintering technology platform enables "Green" Electronic Assemblies

Ormet targeting high growth applications in
PCB and Semiconductor Packaging Materials Markets

Summary



- Ormet is a leader in advanced electrical interconnect materials for PCB and semiconductor applications
- Transient Liquid Phase Sintering materials have many of the advantages of solders and conductive adhesives
 - **Low processing temperature**
 - **High thermal and electrical conductivity**
- Ormet materials enable customers to meet next generation device requirements
 - **Low cost PCBs for mobile applications**
 - **Pb-free assembly materials for Semiconductor Packaging**
 - **High density flash memory packaging for mobile devices**